

Title (en)
PROCESS AND FILM FOR PRODUCING PRINTED WIRING BOARDS

Publication
EP 0351034 B1 19931013 (EN)

Application
EP 89303543 A 19890411

Priority
• JP 17513288 A 19880715
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Abstract (en)
[origin: EP0351034A2] A composite film comprising an additive layer (5) and an insulating layer (4) containing an epoxy resin and a synthetic rubber as major components, is used in the manufacture of printed wiring boards via the additive method. The composite film is laminated on both sides of a substrate, especially an inner layer circuit substrate, and cured. Through-holes are drilled, and the resulting laminate is masked with a plating resist, roughened and electrolessly plated.

IPC 1-7
H05K 3/10; **H05K 3/38**; **H05K 3/44**; **H05K 3/46**

IPC 8 full level
H05K 3/38 (2006.01); **H05K 3/44** (2006.01); **H05K 3/46** (2006.01); **H05K 3/18** (2006.01); **H05K 3/42** (2006.01)

CPC (source: EP KR US)
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Cited by
EP1096842A3; EP1014769A3; EP1720392A3; EP1720393A3; EP0804061A4; WO9717824A1; US9942982B2; US6739040B1; US6217988B1; US6251502B1

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